

IN THE SPECIFICATION

Please replace paragraph [0001] with the following new paragraph:

This application is a divisional of and claims priority to United States patent application serial no. 10/259,352, filed September 30, 2002, which is related to co-pending United States patent application serial no. 10/259,858, entitled “Method and apparatus for an improved upper electrode plate with deposition shield in a plasma processing system”, Attorney docket no. 226272US6YA, filed on September 30, 2002; co-pending United States patent application serial no. 10/259,382, entitled “Method and apparatus for an improved baffle plate in a plasma processing system”, Attorney docket no. 226274US6YA, filed on September 30, 2002; co-pending United States patent application serial no. 10/259,380, entitled “Method and apparatus for an improved baffle plate in a plasma processing system”, Attorney docket no. 228411US6YA, filed on September 30, 2002; co-pending United States patent application serial no. 10/259,353, entitled “Method and apparatus for an improved deposition shield in a plasma processing system”, Attorney docket no. 226275US6YA, filed on September 30, 2002; co-pending United States patent application serial no. 10/259,757, entitled “Method and apparatus for an improved upper electrode plate in a plasma processing system”, Attorney docket no. 225277US6YA, filed on September 30, 2002; and co-pending United States patent application serial no. 10/259,306, entitled “Method and apparatus for an improved bellows shield in a plasma processing system”, Attorney docket no. 226277US6YA, filed on September 30, 2002. The entire contents of all of those applications are herein incorporated by reference in their entirety.